

PROPULSION SYSTEMS

Micro-Propulsion: A limited Introduction

FAMU/FSU College of Engineering

Mechanical Engineering Dept

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Outline

- μ -Spacecraft view point
 - Classification and Applications
- Propulsion Using MEMS
 - MEMS Overview
 - Electro-Thermal Propulsion
 - Chemical Propulsion
 - Digital Micro-Thruster
- Non-MEMS Options
 - Chemical
 - Electro-Thermal
- μ -Propulsion Issues

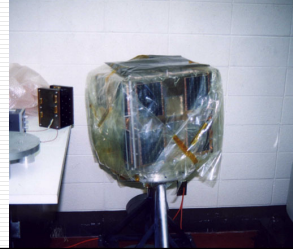
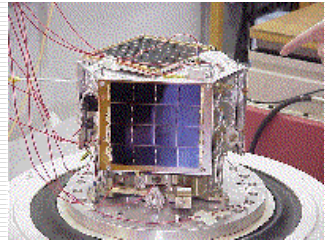

Starting Line

- Massive Field (opportunity)
 - Various applications
 - Numerous Works
- Limit Scope
 - Gives a reference
 - Exclude earth-bound applications
 - Exclude landing and take-off
 - Low thrust
 - μ -Spacecraft!!

Outline

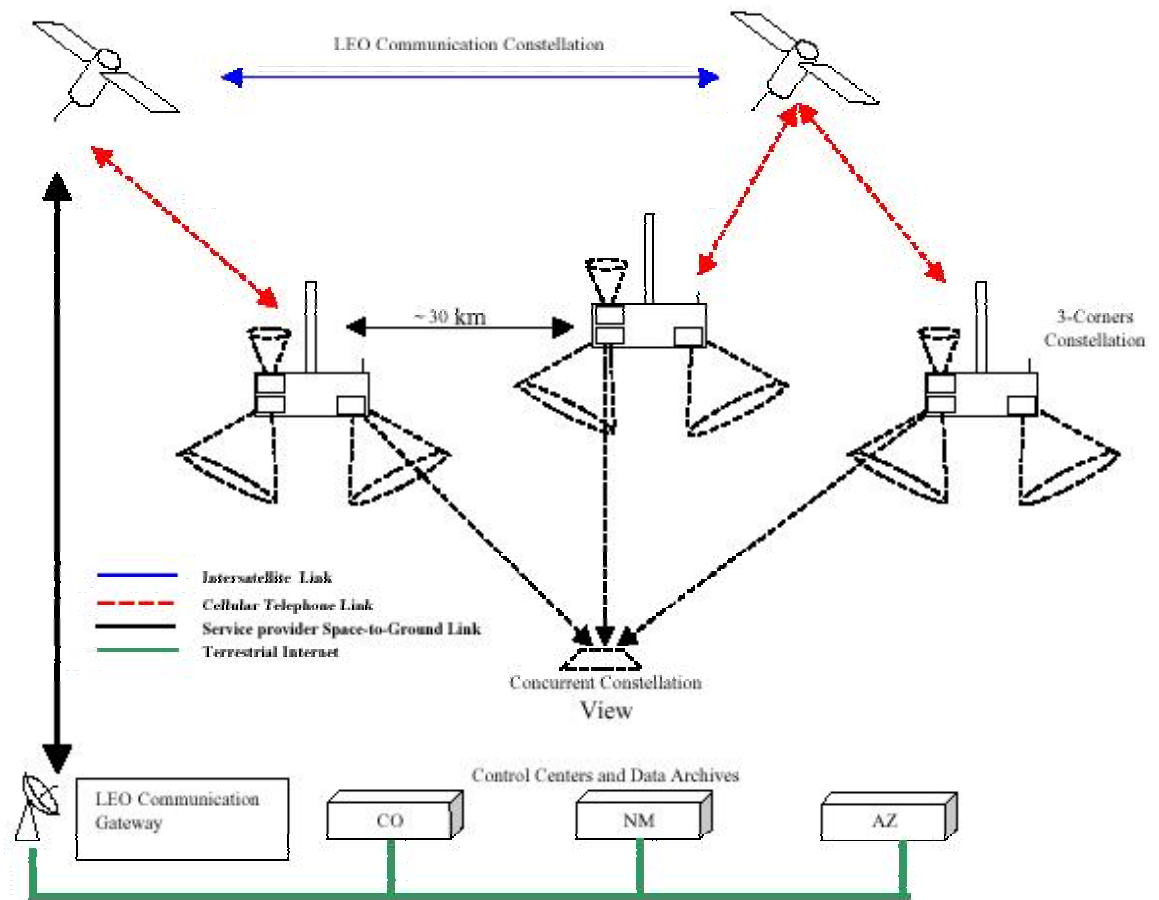
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Categorizing μ -Spacecraft

Designation	Mass (kg)	Power (W)	Dimension (m)	Comment/Picture
Micro-spacecraft	10-100	10-100	0.3-1	
Class I micro-spacecraft	5-20	5-20	0.2-0.4	
Class II micro-spacecraft	1-5	1-5	0.1-0.2	
Class III micro-spacecraft	<1	<1	<0.1	

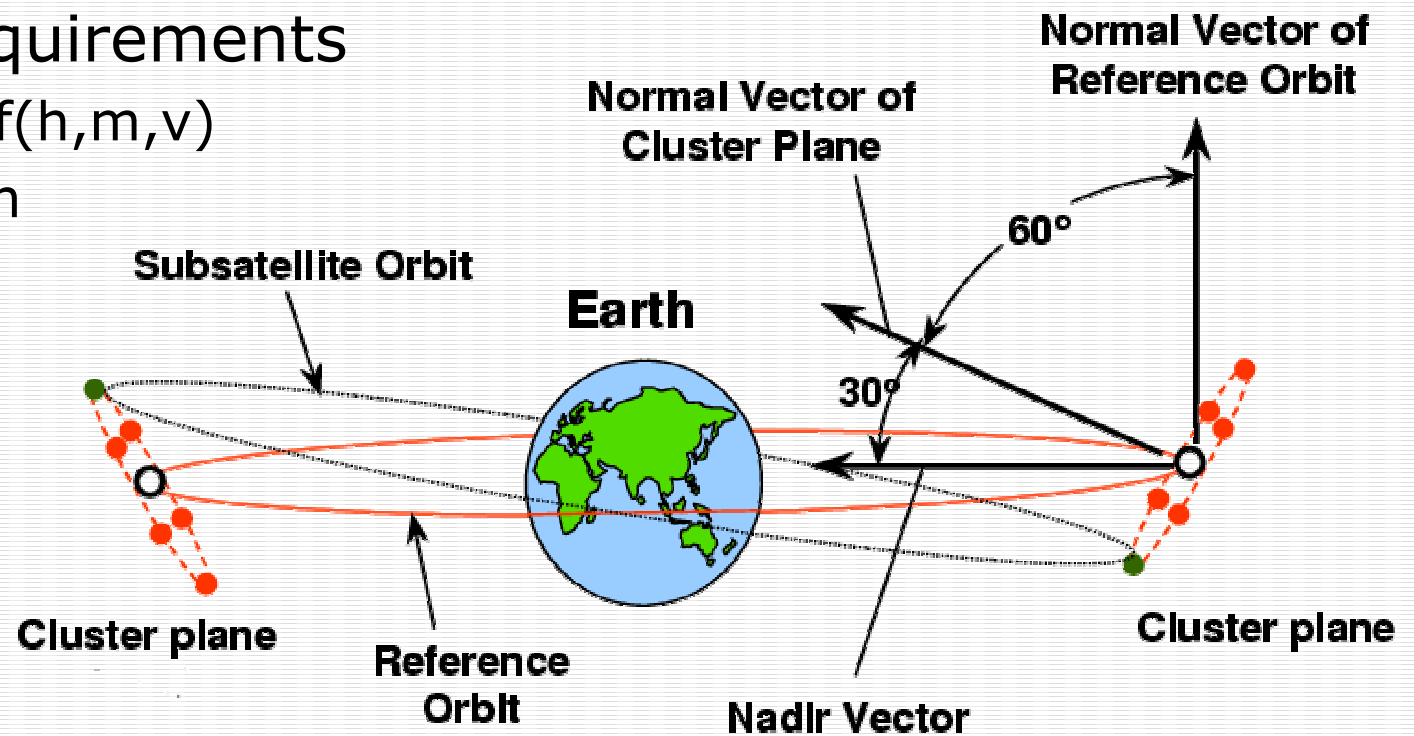
Constellations

- 10-1000m formations
- Parallel or individual
- Direct/LEO Comm.
- 3CS
- Stereoscopic Imaging
- Closed Loop Control



Constellations

- Rigid body rotation
- Orbit Correction Burns: 3/orbit
- ΔV Requirements
 - $\Delta V = f(h, m, v)$
 - $\Delta V \propto h$

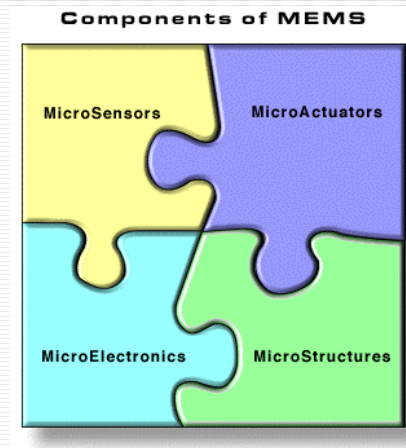
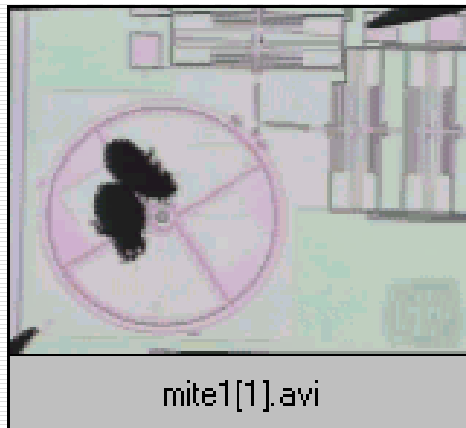


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MEMS

- Micro-Electro-Mechanical Systems
 - Micron-scale
 - Adapted IC technology
 - Systems on chip

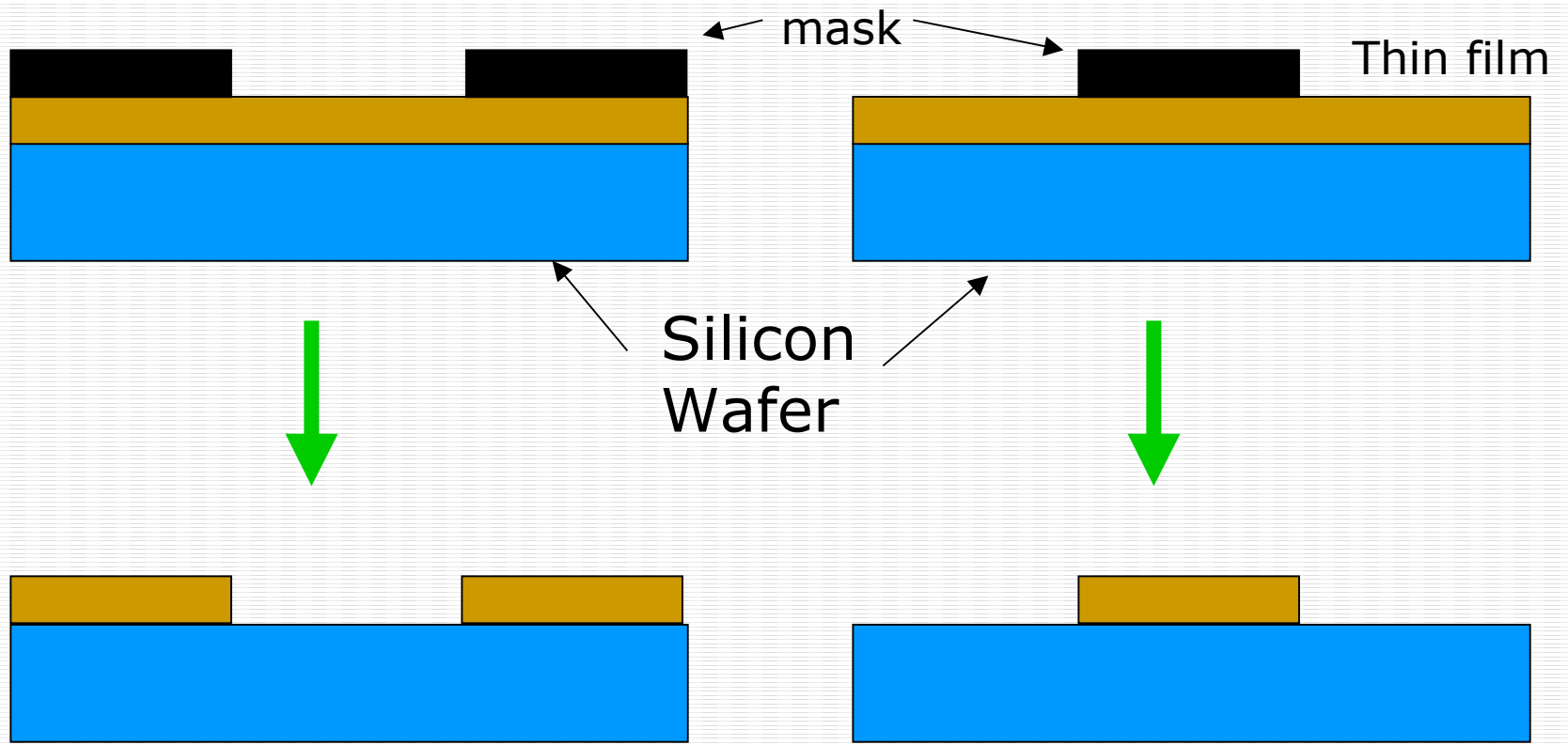


MEMS

- Silicon
 - Sacrificial surface μ -machining or etching
 - Numerous techniques
- Non-Silicon Fabrication
 - New and under development
 - Stronger materials
 - Polymers

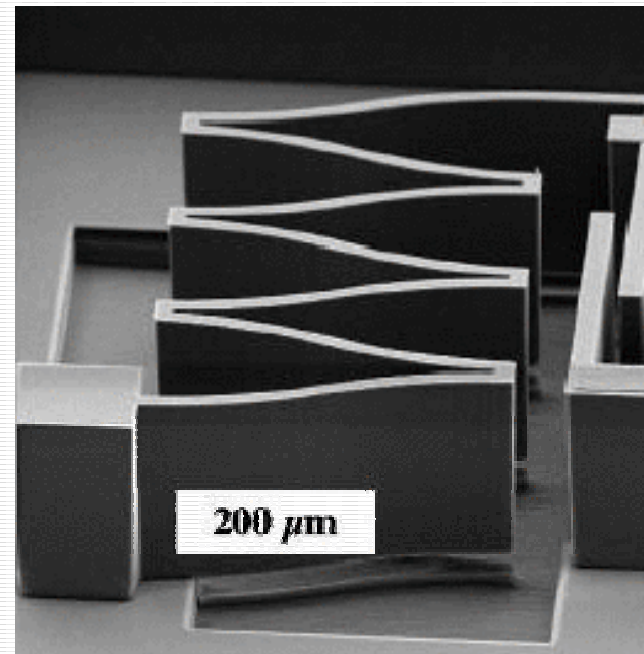
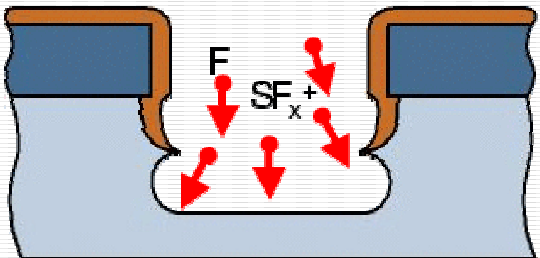
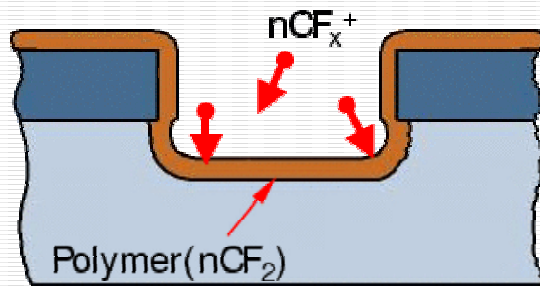
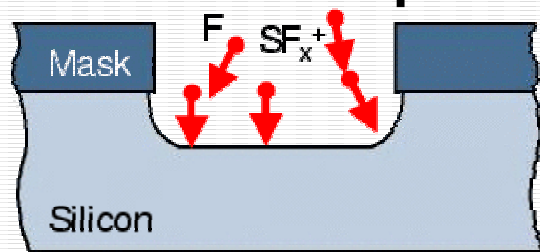
MEMS

■ Anisotropic Wet Etching



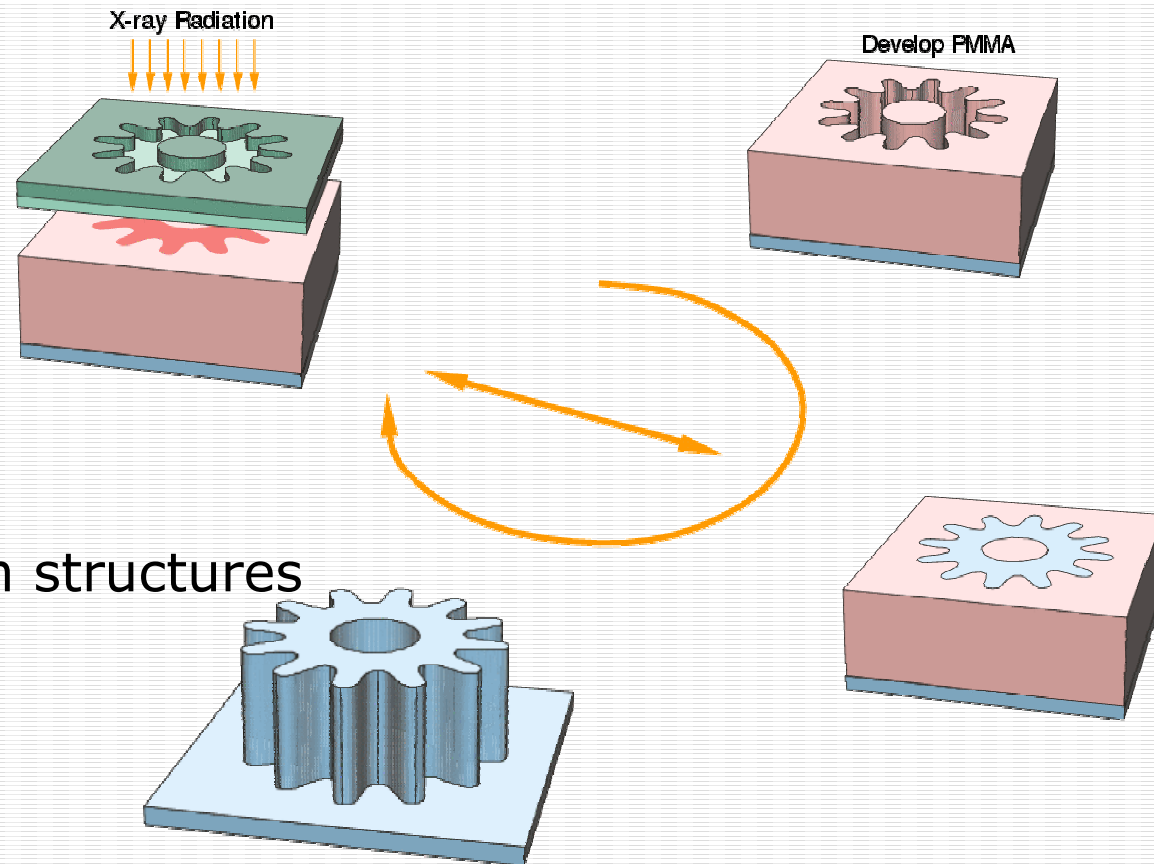
MEMS

■ Anisotropic Dry Etching (RIE)



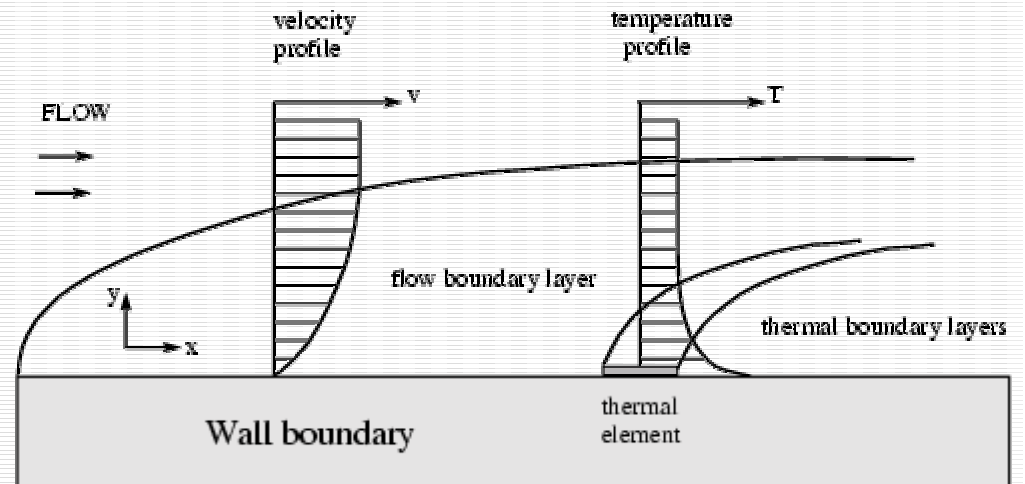
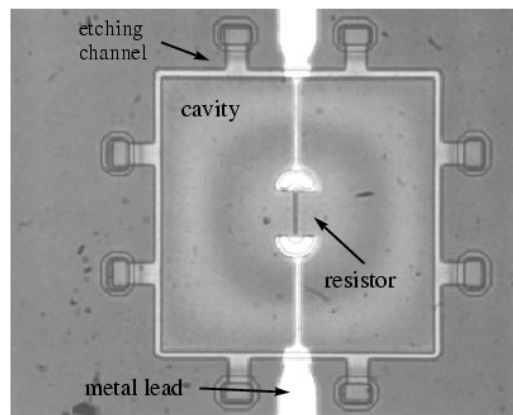
MEMS

- Lithographie Galvanoformung Adformung(LIGA)
- Synchrotron x-ray source (expensive)



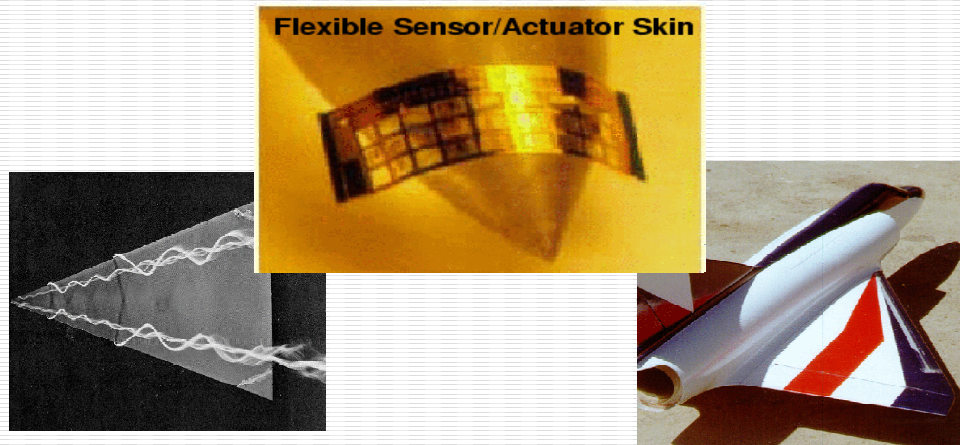
MEMS

- Tools (Shear Stress Sensor)
 - Determine wall shear stress
 - Flush mounted
 - Assumptions allow modeling



MEMS

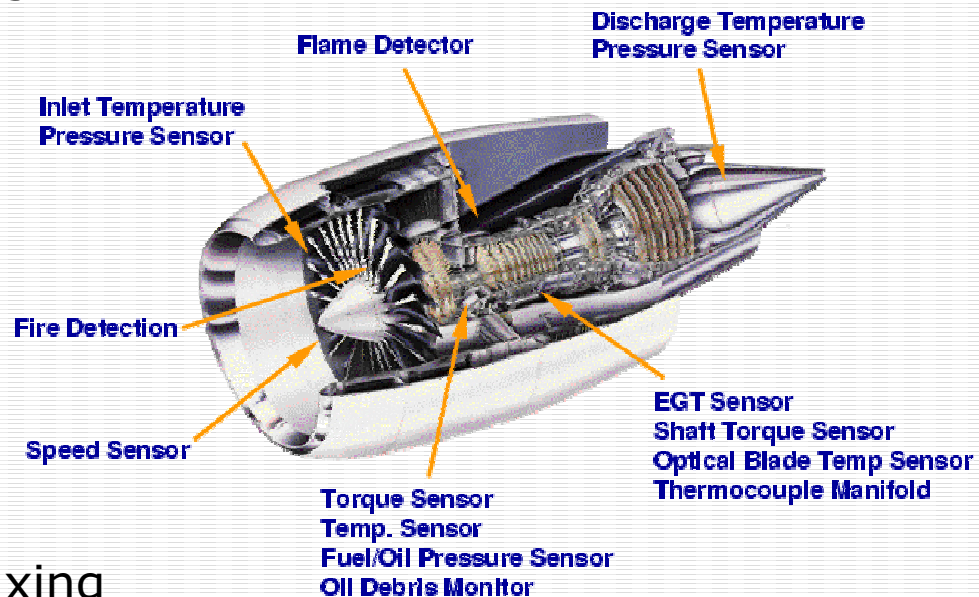
- Research (Vortex-Control: Delta Wing)
 - MEMS actuators and sensors
 - μ -flaps properly located
 - Induce moments for maneuvering



MEMS

■ Propulsion (non-propulsive)

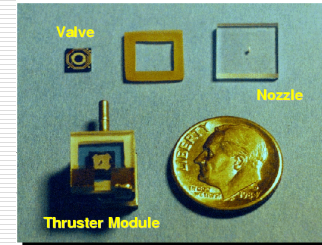
■ Measurements



■ Combustion

- Enhance mixing
- Improve combustion

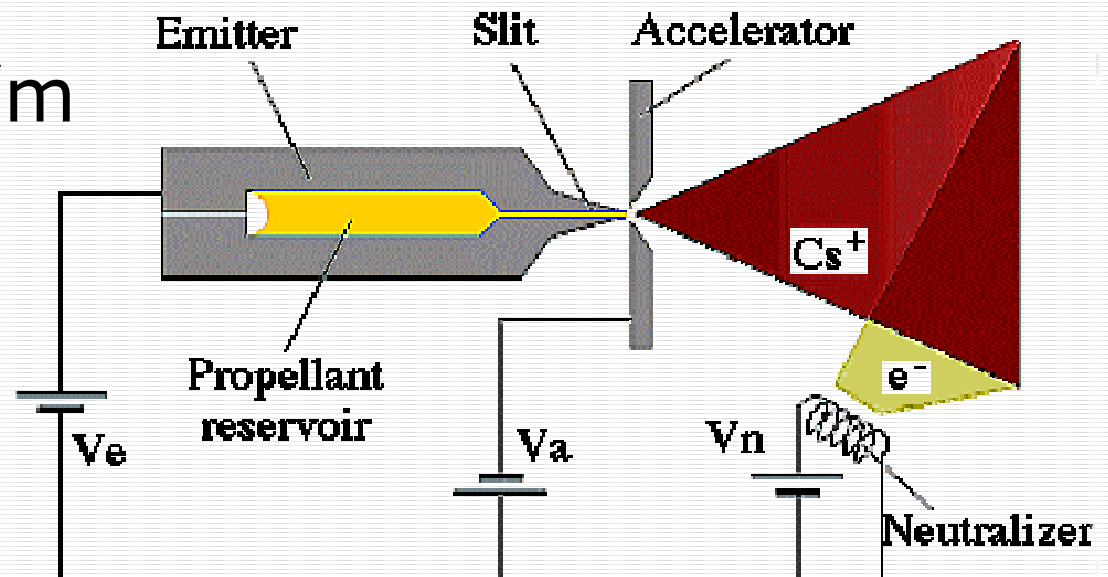
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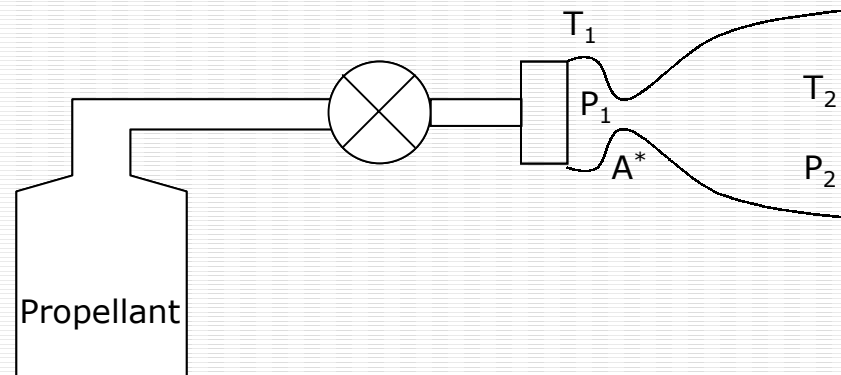
Electro-Thermal (Ion)

- FEEP and Colloid Thrusters
 - $1\mu\text{N} - 1\text{mN}$ Thrust
 - Driven by capillary forces
 - Ion jet
 - $\Delta V = 10^9 \text{ V/m}$
 - Low \dot{m}



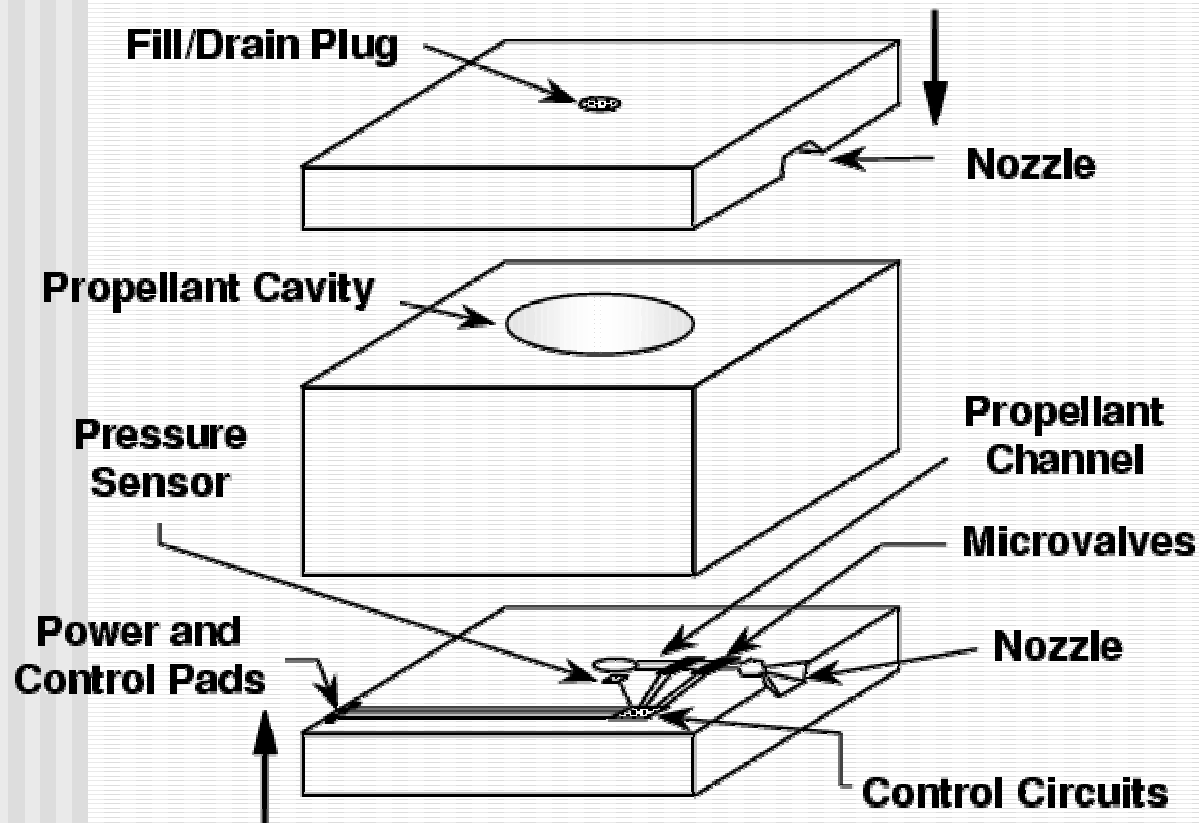
Chemical

- Cold Gas
 - Smallest rocket engines
 - Simple: $v = f(T, P, \gamma)$
 - 0.1mN thrust
 - Scaling Concerns only



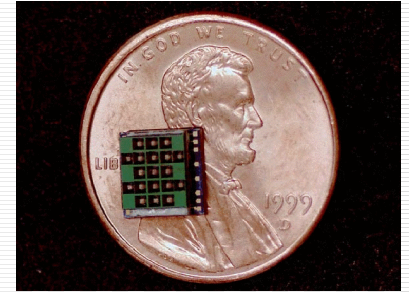
Chemical

■ Cold Gas – Aerospace Corp Version



- Valve leakage
 - High rate
- Choking at valve
 - $10\times \tau$ reduction
 - $27s I_{bit}$

Outline



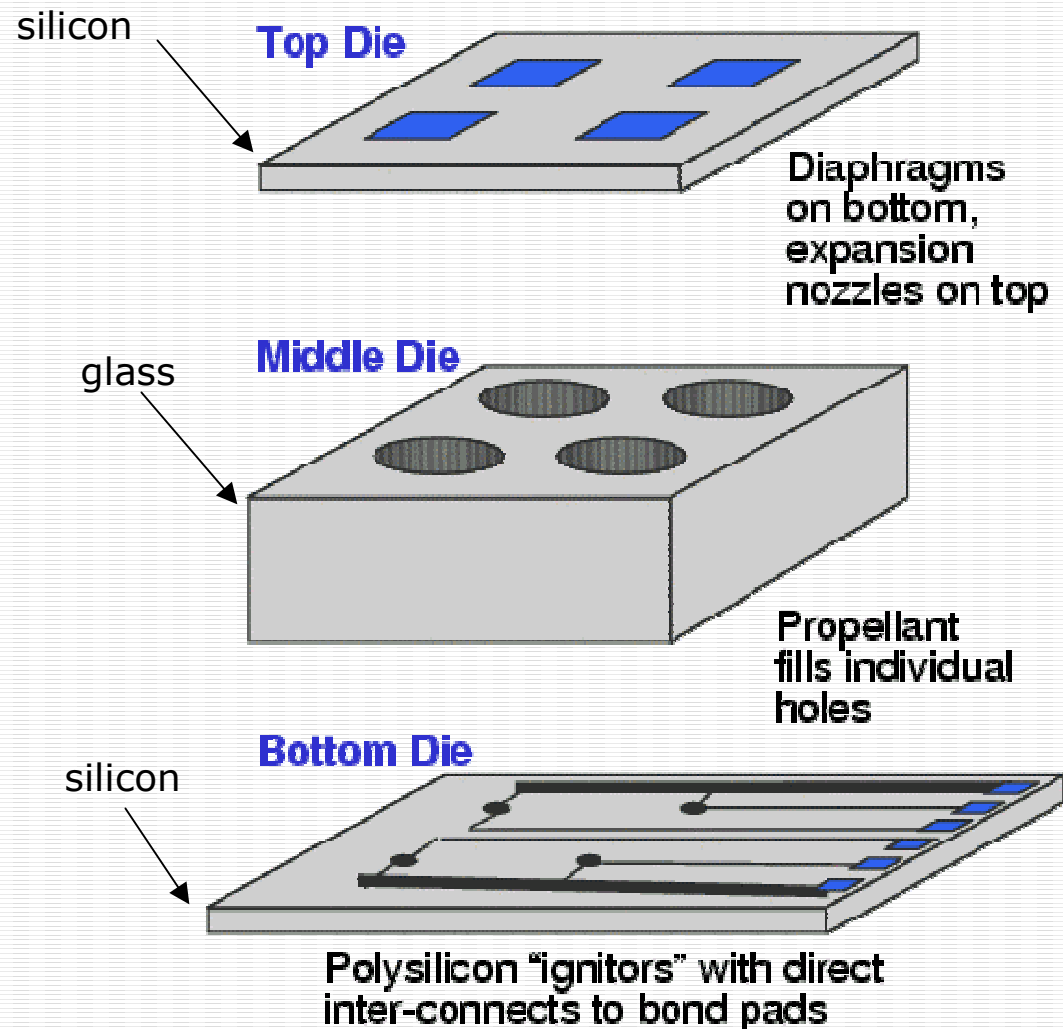
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Digital Micro-thruster

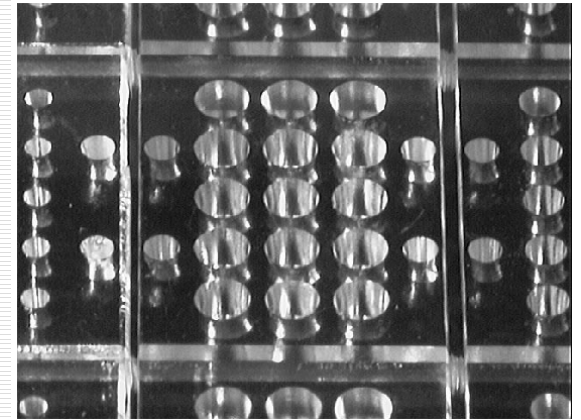
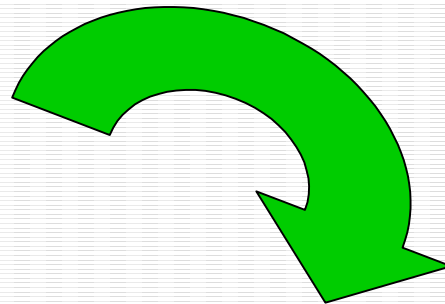
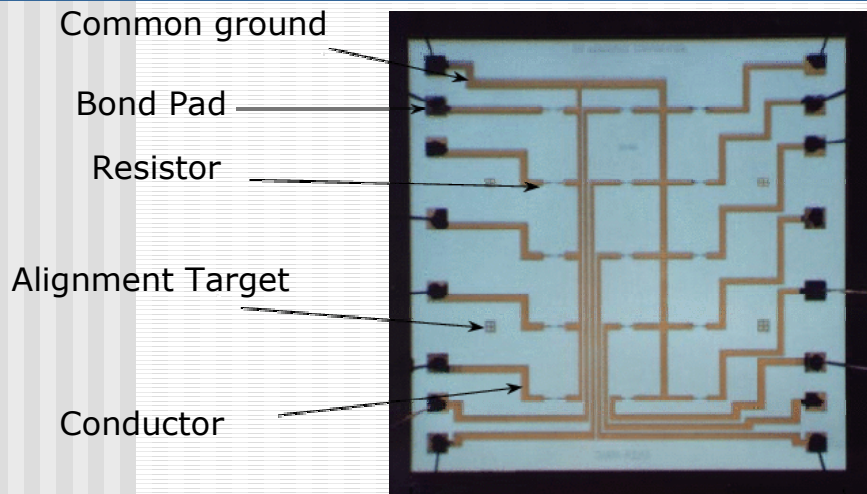
- Multitude of single shot μ -thrusters (10^{-4} to 10^{-6} per 10 cm wafer)
- 10^{-4} to 10^{-6} N-s Impulse bits
- KOH wet etching & wafer bonding
- Class I and II applicability
- Attitude control
- Several Versions
 - TRW/Aerospace Corp
 - French (LAAS at CNRS)
 - Honeywell
 - NASA Glenn

Digital Micro-thruster

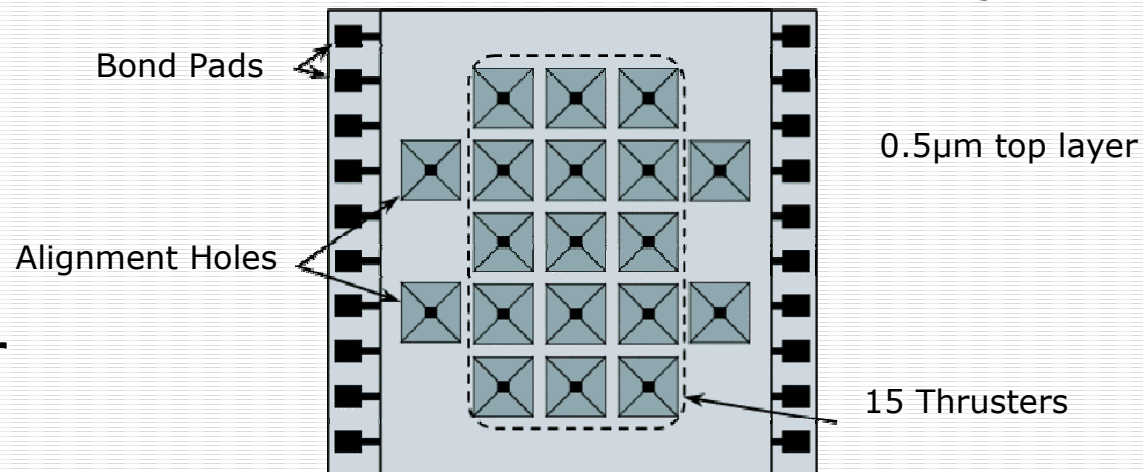
- No tanks, fuel lines, valves
- Integrated with structure
- Propellant: inert or combustible
- No electronics



Digital Micro-thruster

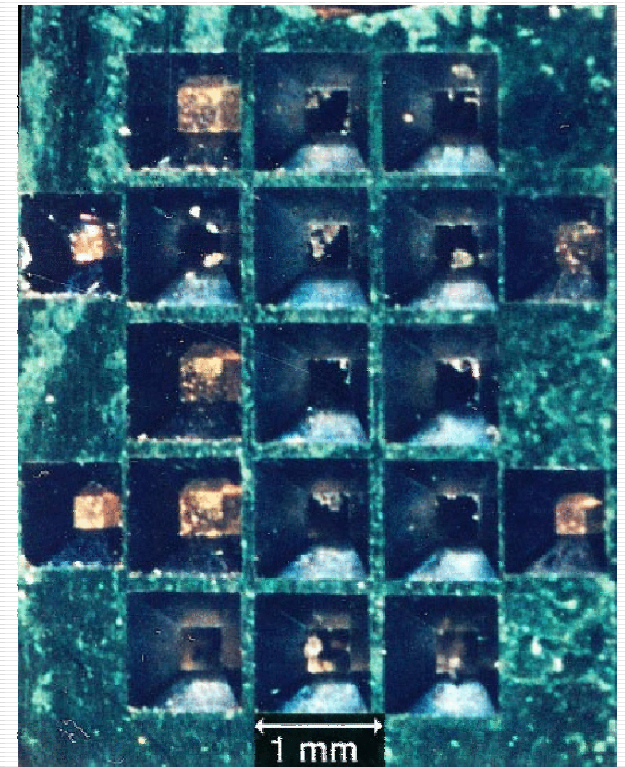
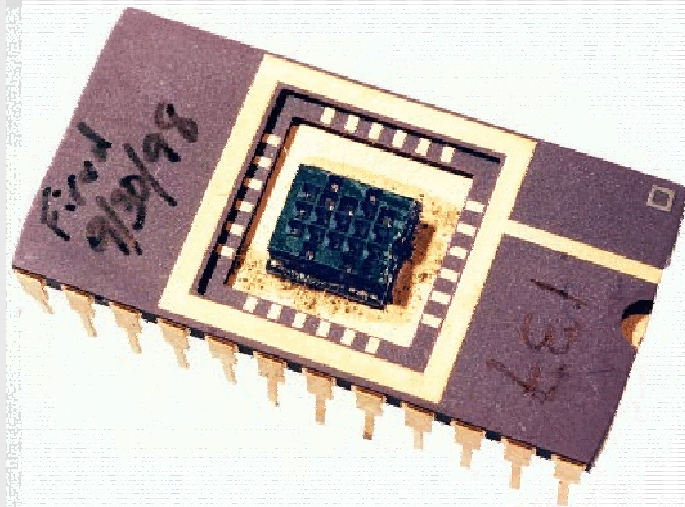


- KOH wet etched
- Three layered wafer



Digital Micro-thruster

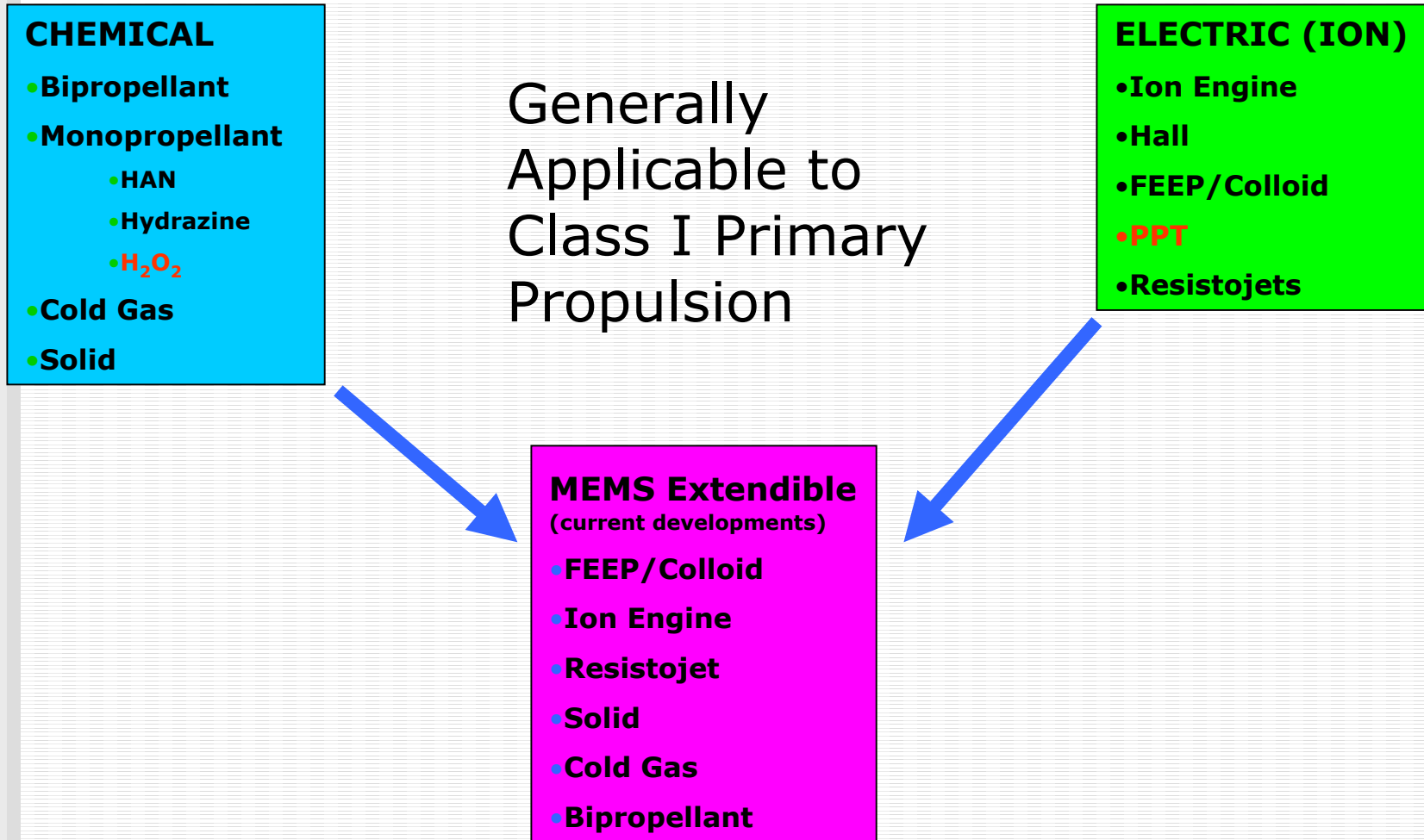
- 10^{-4} N-s with Lead Styphnate
- 1ms impulse duration
- Relatively low ΔV missions
- Ideal for attitude control
- Scales to Meso/Macro



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Non-MEMS Options

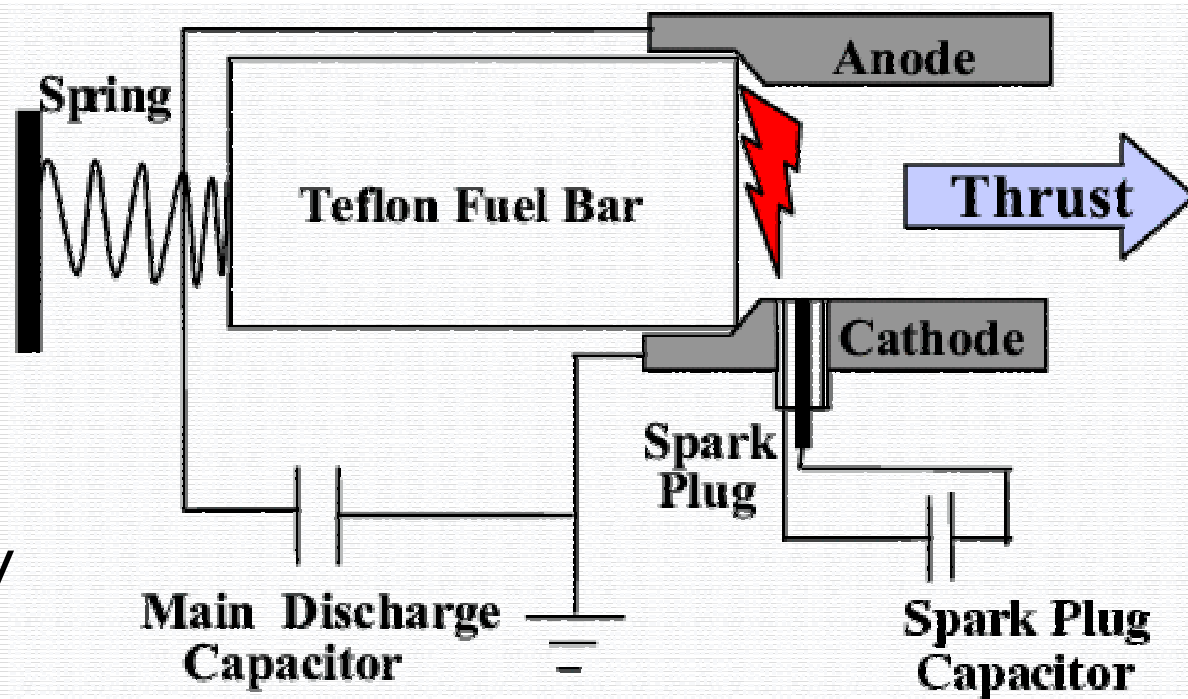


Non-MEMS Options

■ Pulsed Plasma Thruster (PPT)

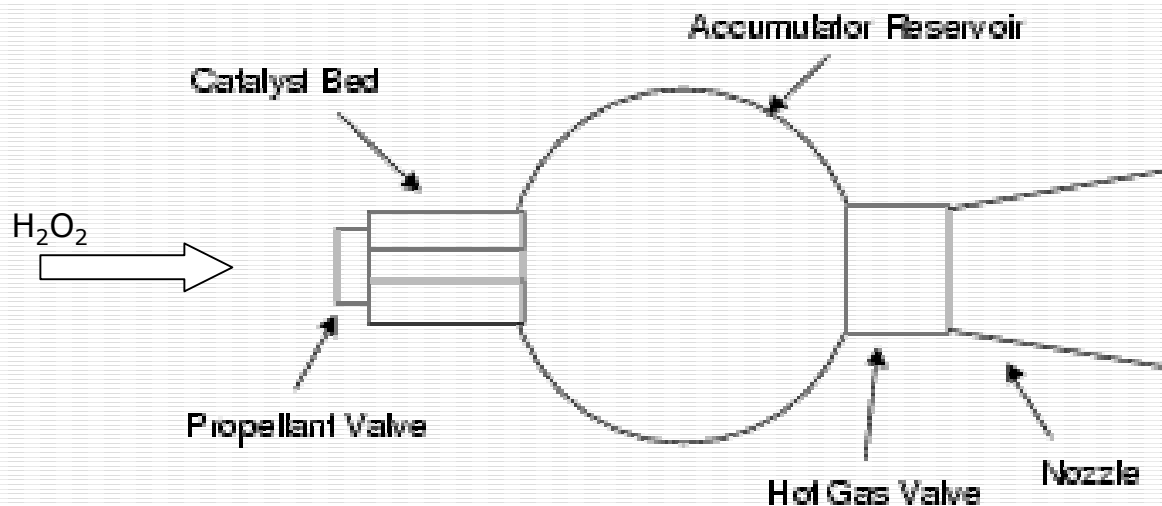
Teflon
"Plasmarized"
by high
current

Plasma
accelerated by
B field



Non-MEMS Options

- Hydrogen Peroxide (H_2O_2)
 - At 90% concentration
 - Silver-wire mesh as catalyst
 - Products: H_2O and heat = steam



Outline

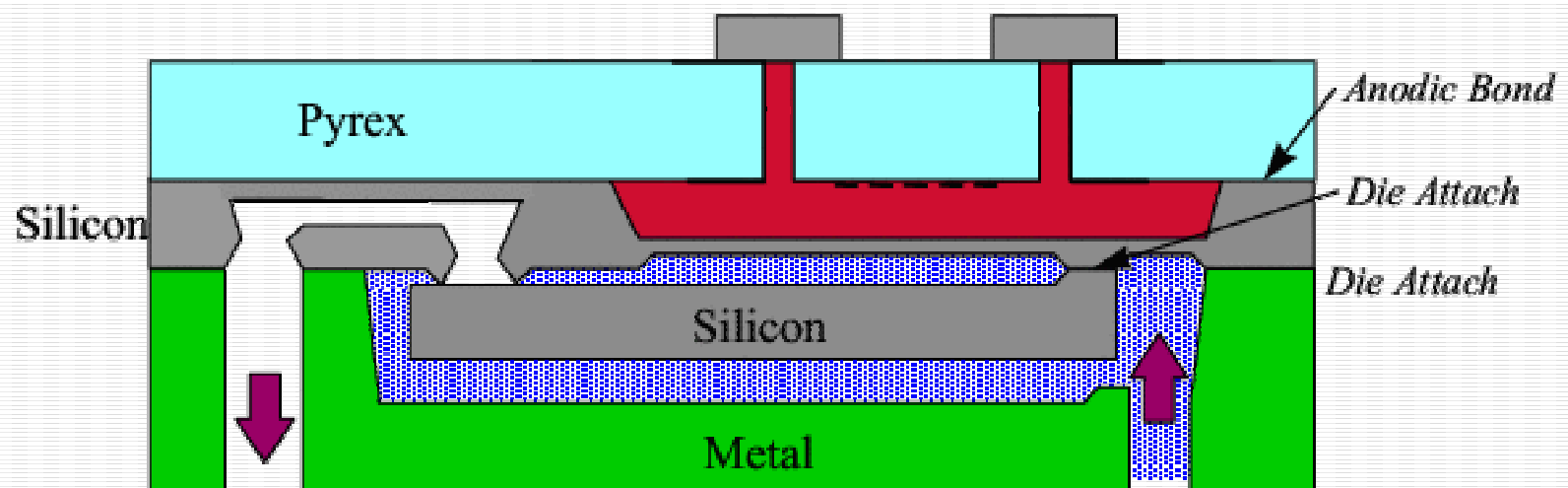
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μ -Propulsion Issues

- Surface effects are dominant
 - BC's change in momentum (gas flows)
- Flows become highly dissipative
- μ -Nozzles
 - ΔP underestimated
 - Currently Several Investigations
- μ -Combustion
 - Incomplete Burn = clogged systems
 - Temps (700 to 1800 K) to high for Silicon
- μ -Heat Effects
 - Thermal Expansion and modeling

μ -Propulsion Issues

- μ -Valves
 - High leak rates
 - Incomplete flow characterizations



Summary

		I_{sp} (sec)	I_{bit} (N-s)	Thrust (N)	Power (W)	μ - Crafft	Class I	Class II	Class III
M E M S									
	FEEP/Colloid		5×10^{-9}	$(1 - 1000) \times 10^{-6}$	2		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	
	Ion Engine						<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	
	Resistojet	48 - 70	Expected arbitrarily small				<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	
	Solid	----	----	-----	-----		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	
	Cold Gas			0.1×10^{-3}			<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	
	Bipropellant						<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	
	Digital		$10^{-4} - 10^{-6}$		100		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	
Non-MEMS									
	Bipropellant	280 - 300		5 - 156		<input checked="" type="checkbox"/>			
	Monopropellant								
	***HAN					<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>		
	***Hydrazine	~220		0.9 - 18		<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>		
	***H ₂ O ₂	65 - 150	0.1	10 - 45		<input checked="" type="checkbox"/>			
	Cold Gas	65 - 296	$10^{-4} - 0.044$	0.0045 - 4.5	2.4 - 30	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>		
	Solid	199 - 273		1.57 - 2500			<input checked="" type="checkbox"/>		
	Ion Engine	1700 - 3700		0.001 - 0.031	50 - 600	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>		
	Hall	830 - 1740		0.0018 - 0.035	70 - 540	<input checked="" type="checkbox"/>			
	FEEP/Colloid	450 - 9000		$7 \times 10^{-6} - 0.0056$		<input checked="" type="checkbox"/>			
	PPT	400 - 5000	$(2 - 860) \times 10^{-6}$	$(0.002 - 2) \times 10^{-3}$	1 - 25	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>		
	Resistojets	----	----	----	----		<input checked="" type="checkbox"/>		

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